

## Full Material Declaration for attached parts list

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## Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved: 13 March 2025 09:18 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	4.8%	Silicon	7440-21-3	100%
			SILVER, ELEMENTAL	7440-22-4	2.5%
			Tin elemental	7440-31-5	5%
Die attach	Sn-Pb solder	3.57%	<b>Elemental lead</b> EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
			Carbon black	1333-86-4	0.85%
			Phenol, polymer with formaldehyde	9003-35-4	1.15%
			Silicon Dioxide	7631-86-9	4%
Encapsulation	EP (Epoxy resin)	25.92%	Epoxy resin 89	26335-32-0	7%
			Quartz sand	60676-86-0	87%
			Copper (e.g. copper amounts in cable harnesses)	7440-50-8	100%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	4.59%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	5.81%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	55.31%	Elemental iron	7439-89-6	2.5%
			COPPER, ELEMENTAL	7440-50-8	97.5%

## Attached parts list

Part number	Part name
QFN5x6 H-Free Cu	Diode / Transistor SMD

